

In the Claims:

Please add new claims 21-24. The claims are as follows:

1. (Original) An integrated circuit package for holding an integrated circuit die and connecting a set of circuit bond pads on the die to a set of package bond pads disposed on a first surface of the package, the package bond pads being arranged in a set of package bond pad modules such that at least one pair of individual package bond pads is disposed with a package bond pad module overlap in an overlap area along a transverse axis extending substantially perpendicular to the die, a first package bond pad of said pair being connected to a first via positioned inward of said overlap area and a second package bond pad of said pair being connected to a second via positioned outward of said overlap area, all of said first package bond pad, said first via, said second package bond pad and said second via being disposed within one of said package bond pad modules and forming a via submodule, each of said package bond pad modules having a package module pitch along a longitudinal axis parallel to a side of said integrated circuit die.
2. (Original) A package according to claim 1, in which each package bond pad module contains a subset of bond pads equal in number to a corresponding number of circuit bond pads disposed in said die within said package module pitch.
3. (Original) A package according to claim 1, in which at least one connection for DC power passes through a via submodule located along said transverse axis at a first position.

4. (Original) A package according to claim 3, in which at least two connections for DC power pass through corresponding first and second via submodules located at said first position along said transverse axis and in separate package bond pad modules.

5. (Original) A package according to claim 1, in which no connection for DC power passes along a conductive member that passes substantially parallel to a longitudinal axis substantially perpendicular to said transverse axis through substantially all of a subset of package bond pad modules on an edge of said die.

6. (Original) A package according to claim 5, in which at least one connection for DC power passes through a via submodule located along said transverse axis at a first position.

7. (Original) A package according to claim 6, in which at least two connections for DC power pass through a single via submodule located at a first position along said transverse axis.

8. (Original) A package according to claim 7, in which at least two connections for DC power pass through corresponding first and second via submodules located at said first position along said transverse axis and in separate package bond pad modules.

9. (Original) A package according to claim 6, in which no connection for DC power passes along a conductive member that passes substantially parallel to a longitudinal axis substantially perpendicular to said transverse axis through substantially all of a subset of package bond pad

modules on an edge of said die.

10. (Original) An integrated circuit package for holding an integrated circuit die and connecting a set of circuit bond pads on the die to a set of package bond pads disposed on a first surface of the package, the package bond pads being arranged in a set of package bond pad modules such that at least two pairs of individual package bond pads are disposed having a package bond pad module overlap in at least two overlap areas along a transverse axis extending substantially perpendicular to the die, a first package bond pad of each of said pairs being connected to a first via positioned inward of said overlap area and a second package bond pad of each of said pairs being connected to a second via positioned outward of said overlap area, all of said pairs of package bond pads and associated vias being disposed within one of said package bond pad modules and forming a via submodule, each of said package bond pad modules having a package module pitch along a longitudinal axis parallel to a side of said integrated circuit die.

11. (Original) A package according to claim 10, in which each package bond pad module contains a subset of bond pads equal in number to a corresponding number of circuit bond pads disposed in said die within said package module pitch.

12. (Original) A package according to claim 10, in which at least one connection for DC power passes through a via submodule located along said transverse axis at a first position.

13. (Original) A package according to claim 12, in which at least two connections for DC power

pass through corresponding first and second via submodules located at said first position along said transverse axis and in separate package bond pad modules.

14. (Original) A package according to claim 10, in which no connection for DC power passes along a conductive member that passes substantially parallel to a longitudinal axis substantially perpendicular to said transverse axis through substantially all of a subset of package bond pad modules on an edge of said die.

15. (Original) A package according to claim 14, in which each package bond pad module contains a subset of bond pads equal in number to a corresponding number of circuit bond pads disposed in said die within said package module pitch.

16. (Original) A package according to claim 10, in which at least one connection for DC power passes through a via submodule located along said transverse axis at a first position.

17. (Original) A package according to claim 10, in which at least two connections for DC power pass through a single via submodule located at a first position along said transverse axis.

18. (Original) A method of forming an integrated circuit package for holding an integrated circuit die and connecting a set of circuit bond pads on the die to a set of package bond pads disposed on a first surface of the package, the package bond pads being arranged in a set of package bond pad modules such that at least one pair of individual package bond pads is disposed in a package bond

pad module overlap in an overlap area along a transverse axis extending substantially perpendicular to the die comprising the steps of:

forming an insulating substrate including a set of vias extending from a top surface to a set of lower interconnection members;

forming said set of bond pad modules, including forming said pair of individual package bond pads with a first package bond pad of said pair being connected to a first via positioned inward of said overlap area and a second package bond pad of said pair being connected to a second via positioned outward of said overlap area, all of said first package bond pad, said first via, said second package bond pad and said second via being disposed within one of said package bond pad modules and forming a via submodule, such that each of said package bond pad modules has a package module pitch along a longitudinal axis parallel to a side of said integrated circuit die.

19. (Original) A package according to claim 18, further comprising a step of forming at least one connection for DC power passing through a via submodule located along said transverse axis at a first position.

20. (Original) A package according to claim 18, further comprising a step of forming at least two connections for DC power passing through corresponding first and second via submodules located at said first position along said transverse axis and in separate package bond pad modules.

21. (New) The method of claim 1, wherein no edge of the first package bond pad is not aligned with any edge of the first via.

22. (New) The method of claim 21, wherein no edge of the second package bond pad is not aligned with any edge of the second via.

23. (New) The method of claim 21, wherein an edge of the second package bond pad is aligned with an edge of the second via.

24. (New) The method of claim 1, wherein a lower edge of the first package bond pad is aligned with a lower edge of the first via, and wherein an upper edge of the second package bond pad is aligned with an upper edge of the second via.